ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES INTERNATION CONNECTING International and Pan-Am	Bannockburn, Illinois.	All rights reserved us entions.	nder both Iev	nis docume vel parts, t	ent is a declaration he declaration en	n of the substance compasses all lov	es within the manufactur ver level materials for w	er listed item	. Note: if the second sec	he item is an as as engineering	sembly with lower responsibility.	
	.1 IPC Web Site for Information on IPC-1752 Standard Form Distr			 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and 				als and Mfg I	and Mfg Information			
Supplier Information												
Company name*	nique ID	que ID t			Unique ID Authority				Response Date*			
isemi								2024-04-20				
tact Name Title - Contact]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Enviro Complia			pliance NA		NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			Phone - Representative*			ntative*	Email - Representative*					
Product-Env-Stewards Product Enviro Complian			npliance NA		JA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		ght*	UOM	Unit Type	
	LED DR, 16 CH		4-WIRE I/F	RE I/F 2024-			TH5		5	mg	Each	
Manufacturing Proccess Information					•					•	·	
Terminal Plating / Grid Array Materia	I Terminal Bas	e Alloy J	J-STD-020 MSL Rating		Peak Process Body Temperature		ture Max Time at Peak	Temperature Number of Reflow Cycles			les	
Matte Tin (Sn) - annealed CU Alloy		1	1		260	С	30	seconds	3			
Comments												
level 1 - maximum time at peak temperature d	uring soldering is 10	-30 seconds										
For more information regarding material com	position please refer	to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a that agreement, will be the sole and exclusives	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe ve independently verified such information. How heir contributions to the part, and those certifica anditions of that agreement, including any warr	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	pplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of e Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the erms andConditions of Sale applicable to such part shall apply. ontain RoHS restricted substances per the definition above Supplier Acceptance * Accepted IS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.51	mg	Supplier	Silicon (Si)	7440-21-3		5.51	mg
Die Attach 0.6	0.61	mg	Supplier	Silver (Ag)	7440-22-4		0.4575	mg
			Supplier	Epoxy resins	129915-35-1		0.1525	mg
Lead Frame 27.	27.38	mg	Supplier	Silver (Ag)	7440-22-4		0.8241	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0411	mg
			Supplier	Silicon (Si)	7440-21-3		0.178	mg
			В	Nickel (Ni)	7440-02-0		0.8214	mg
			Supplier	Copper (Cu)	7440-50-8		25.5154	mg
Mold Compound-Black	53.25	mg		Epoxy Phenol Resin	proprietary data		5.5912	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		47.6587	mg
Plating	2.58	mg	Supplier	Tin (Sn)	7440-31-5		2.58	mg
Wire Bond - Au	0.72	mg	Supplier	Gold (Au)	7440-57-5		0.72	mg